

## UNAPPROVED MINUTES

### IEEE 802.3 Ethernet Working Group

#### Plenary Opening Meeting

9-Mar 2026

<https://www.ieee802.org/3/minutes/mar26/index.html>

**MONDAY, 9-MAR 2026**

Minutes were taken by IEEE recording secretary Jon Lewis.

#### ADMINISTRATIVE MATTERS

##### Call to order

David Law, Chair of the IEEE 802.3 Ethernet Working Group, called the meeting to order at 10:15 PDT.

##### Welcome, introductions, and general announcements

Mr. Law noted that it would be too time consuming to have each individual introduce themselves, that introductions would not be done at this hybrid meeting.

Mr. Law showed a list of officers of the IEEE 802.3 Working Group:

IEEE 802.3 Chair: David Law

IEEE 802.3 Vice-Chair: Adam Healey

IEEE 802.3 Secretary: Jon Lewis

IEEE 802.3 Executive Secretary: Chad Jones

IEEE 802.3 Treasurer: Valerie Maguire

##### IEEE 802.3 Task Force chairs

IEEE P802.3da 10SPE Multidrop Enhancements: Chad Jones

IEEE P802.3dg 100 Mb/s Long-Reach Single Pair Ethernet: George Zimmerman

IEEE P802.3dj 200 Gb/s, 400 Gb/s, 800 Gb/s, and 1.6 Tb/s Ethernet: John D'Ambrosia

IEEE P802.3dk Greater than 50 Gb/s Bidirectional Optical Access PHYs: Yuanqiu Luo

IEEE P802.3dm Asymmetrical Electrical Automotive Ethernet: Natalie Wienckowski

IEEE P802.3dp Cabling Restrictions for Single Pair Power over Ethernet: Chad Jones

IEEE P802.3dq Pin-Optimized PHY Interface: Jason Potterf

IEEE Std 802.3-2022/Cor 2 (IEEE 802.3dr) Optical Automotive Ethernet TDFOM: Luisma Torres

IEEE P802.3ds 200 Gb/s per Wavelength MMF PHYs: Mabud Choudhury

IEEE P802.3dt Ethernet Metadata Services (Pro Tem): David Ofelt

##### IEEE 802.3 Task Force vice-chairs

IEEE P802.3dj 200 Gb/s, 400 Gb/s, 800 Gb/s, and 1.6 Tb/s Ethernet: Mark Nowell

IEEE P802.3dm Asymmetrical Electrical Automotive Ethernet: Steve Gorshe

## Working Group Decorum

Mr. Law introduced the Working Group decorum as described in the opening report. Please see [https://www.ieee802.org/3/minutes/mar26/0326\\_802\\_3\\_opening\\_plenary.pdf#page=3](https://www.ieee802.org/3/minutes/mar26/0326_802_3_opening_plenary.pdf#page=3) .

Mr. Law noted that there should be no recording without permission and that recording was disabled for this meeting in the teleconference tool.

Mr. Law noted that there was a change in the procedures for members of the press in the 2026 IEEE-SA Standards Board Operations manual. He then asked if anyone was attending from the press including those who would run a public blog on this meeting other than those limited to summarizing the meeting. There was no response.

Mr. Law introduced Mr. D'Ambrosia who reminded the group of the procedure for participants including adding their affiliation in their screen name and noted other zoom guidelines for in-person and remote participants including the operation of the queues. Please see

[https://www.ieee802.org/3/minutes/mar26/0326\\_802\\_3\\_opening\\_plenary.pdf#page=6](https://www.ieee802.org/3/minutes/mar26/0326_802_3_opening_plenary.pdf#page=6) .

Mr. Law informed the group that the this plenary meeting is subject to a registration fee and that there are penalties for non-payment of registration fees.

[https://www.ieee802.org/3/minutes/mar26/0326\\_802\\_3\\_opening\\_plenary.pdf#page=8](https://www.ieee802.org/3/minutes/mar26/0326_802_3_opening_plenary.pdf#page=8) .

## Review and approval of agenda

Mr. Law noted that a soft copy of the draft agenda had been posted to the minutes section for this meeting.

Mr. Law asked if there were any modifications to the draft agenda.

### MOTION #1

Approve the agenda as posted.

M: J. D'Ambrosia

S: K. Lusted

Procedural (> 50%)

Motion Passed by unanimous consent 9-Mar 2026, 10:26 PDT

### MOTION #2

Approve the Nov 2025 plenary minutes as posted.

M: K. Lusted

S: N. Weinckowski

Procedural (> 50%)

Motion Passed by unanimous consent 9-Mar 2026, 10:27 PDT

## Call for patents

Please see: [https://www.ieee802.org/3/minutes/mar26/0326\\_802\\_3\\_opening\\_plenary.pdf#page=11](https://www.ieee802.org/3/minutes/mar26/0326_802_3_opening_plenary.pdf#page=11)

Mr. Law showed the IEEE patent policy slides and asked if anyone has not seen the patent policy before, no one responded.

Mr. Law asked if anyone was aware of any patent claims potentially essential to the proposed standards under development by the IEEE 802.3 Working Group. There was no response.

Mr. Law asked that Mr. Lewis record that:

The patent policy, per the latest PatCom slide set, was shown

There was no response to the call for potentially essential patent claims

Anyone wishing to submit a letter of assurance can do so at any time by contacting Mr. Law or the PatCom administrator

Mr. Law reminded the group of inappropriate topics that should not be discussed. These included territory, market share, price, ongoing litigation, threatened litigation, etc.

Mr. Law asked if anyone had not seen the copyright slides previously, no one responded, and he proceeded to review the IEEE SA copyright slides.

[https://www.ieee802.org/3/minutes/mar26/0326\\_802\\_3\\_opening\\_plenary.pdf#page=16](https://www.ieee802.org/3/minutes/mar26/0326_802_3_opening_plenary.pdf#page=16)

Mr. Law advised participants that:

- IEEE SA's copyright policy is described in Clause 7 of the IEEE SA Standards Board Bylaws and Clause 6.1 of the IEEE SA Standards Board Operations Manual;
- Prior to presentation or submission, you shall notify the Working Group Chair of previously Published material and should assist the Chair in obtaining copyright permission acceptable to IEEE SA. For material that is not previously Published, IEEE is automatically granted a license to use any material that is presented or submitted.

Mr. Law asked if anyone had not seen the participation slides previously, no one responded. He then reviewed the IEEE SA participation slides and highlighted the two new slides (Pages 22 and 23).

[https://www.ieee802.org/3/minutes/mar26/0326\\_802\\_3\\_opening\\_plenary.pdf#page=19](https://www.ieee802.org/3/minutes/mar26/0326_802_3_opening_plenary.pdf#page=19)

Mr. Law advised participants that:

- Participants in the IEEE-SA "individual process" under which the project operates shall act independently of others, including employers, and shall act based on their qualifications and experience. By participating in standards activities using the "individual process", you are deemed to accept these requirements; if you are unable to satisfy these requirements then you shall immediately cease any participation.

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Mr. Law advised participants that in IEEE SA Activities are bound to the following:

- No participant may exercise "authority, leadership, or influence by reason of superior leverage, strength, or representation to the exclusion of fair and equitable consideration of other viewpoints" or "to hinder the progress of the standards development activity"

- Participants in attendance at IEEE SA Standards development activity meetings shall adhere to appropriate meeting decorum, and IEEE SA meeting rules, Recording is not permitted. Participants intending to report publicly on this meeting (e.g., via news outlets, social media, or online forums) shall inform the Chair of their attendance and the Chair shall announce their presence and their intent to report publicly.
- Participants shall comply with IEEE SA Standards Board Operations Manual 5.1.4 Standards promotion and social media communication requirements.
- Participants can contact the IEEE concerning alleged violations of IEEE's Code of Conduct, Code of Ethics, or other policies and rules using the information given.

### **General Working Group business**

Mr. Law explained the membership requirements (gaining):

- Attendance in at least 75% of meeting slots<sup>1</sup> at 2 of the last 4 plenary sessions
  - Attendance in at least 75% of meeting slots at recent IEEE 802.3 Ethernet Working Group or Task Group Interim Session may be substituted for one of the two Plenary Sessions
- Attendance in at least 75% of the meeting slot's duration is required for that attendance to count towards gaining or maintaining voting membership
- Maintain valid contact information
- Consistent declaration of affiliation
- Request to become member during potential voter agenda item at an IEEE 802.3 Ethernet Working Group opening or closing **plenary** meeting

Membership requirements (retaining)

- Continue to meet above attendance, contact, and affiliation requirements
- Participate in two out of the last three Working Group Letter Ballot Series

Mr. Lewis reviewed the membership and attendance tool procedures.

[https://www.ieee802.org/3/minutes/mar26/0326\\_802\\_3\\_opening\\_plenary.pdf#page=27](https://www.ieee802.org/3/minutes/mar26/0326_802_3_opening_plenary.pdf#page=27)

Please see <http://ieee802.org/3/rules/index.html> for complete information.

Mr. Law asked the group to take a moment and sign in to IMAT.

#### Review of voting membership

Please [https://www.ieee802.org/3/minutes/mar26/0326\\_voters.pdf](https://www.ieee802.org/3/minutes/mar26/0326_voters.pdf)

#### Review of voters in peril

Please [https://www.ieee802.org/3/minutes/mar26/0326\\_peril.pdf](https://www.ieee802.org/3/minutes/mar26/0326_peril.pdf)

#### Review of Potential voters

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<sup>1</sup> There are four IMAT meeting slots during the day during plenary and credited interim sessions

Please see [https://www.ieee802.org/3/minutes/mar26/0326\\_potential.pdf](https://www.ieee802.org/3/minutes/mar26/0326_potential.pdf)

The following participants requested voting rights during the opening plenary:

Castro, Jose	Hogenmueller, Thomas	Ng, Hiok Tiaq
Chan, Jason	Hong, Paul	Pal, Debajyoti
Cheng, Xiaoyue	Jin, Robert	Pan, Chunpo
Dai, Shaoran	Jochim, Markus	Pandey, Sujan
Dalmia, Kamal	Kandarpa, Venkata	Quan, Yu
Djahanshahi, Hormoz	Kapoor, Samay	Rajagopal, Karthik
Dsilva, Hansel	Lee, Sylvanus	Royer, Tyler
Estrakh, Daniel	Lewis, David	Veloso Cauce, Gumersindo
Goel, Sachin	Lin, Youxi	Wei, Terry
He, Michael	Nagaraja, Srikanth	Zhang, Wei

Val Maguire presented the Working Group treasury report. Please see

[https://www.ieee802.org/3/minutes/mar26/0326\\_treasury.pdf](https://www.ieee802.org/3/minutes/mar26/0326_treasury.pdf)

Mr. Lewis displayed a list of the voters that requested voting rights in the opening plenary. Mr. Law asked if any new voter that had requested voting rights and were not shown correctly. There was no response.

Mr. Law showed the IEEE 802 LMSC report and meeting schedule. Please see

[https://www.ieee802.org/3/minutes/mar26/0326\\_802\\_3\\_opening\\_plenary.pdf#page=34](https://www.ieee802.org/3/minutes/mar26/0326_802_3_opening_plenary.pdf#page=34)

Mr. Law introduced the In-Person Collaboration being considered at the LMSC and noted that there would be discussing this topic at the closing plenary meeting on Thursday.

Mr. Law showed the instructions for accessing the IEEE 802 eMedia.

[https://www.ieee802.org/3/minutes/mar26/0326\\_802\\_3\\_opening\\_plenary.pdf#page=38](https://www.ieee802.org/3/minutes/mar26/0326_802_3_opening_plenary.pdf#page=38)

Mr. Law showed the other IEEE 802 LMSC PARs under consideration at the plenary session.

[https://www.ieee802.org/3/minutes/mar26/0326\\_802\\_3\\_opening\\_plenary.pdf#page=40](https://www.ieee802.org/3/minutes/mar26/0326_802_3_opening_plenary.pdf#page=40)

Mr. Lusted reported that there are no PAR for consideration and that the ad hoc didn't meet.

## LIAISONS

### External Liaison letters (old)

ITU-T SG15 Updates to ANT and HNT Standards Overviews and Work Plans [liaison letter](#)

ITU-T SG15 Update to OTNT Standards Overview and Work Plan [liaison letter](#) and [attachment](#)

ITU-T SG15 Development of weakly-coupled multi-core fibre Recommendations [liaison letter](#)

ITU-T SG15 Approval of Technical Report on International Optical Networks towards 2030 (ION-2030) and Beyond [liaison letter](#) and [attachment](#)

ITU-T SG15 Technical report of use cases and requirements beyond 10Gbps [liaison letter](#)

OIF: Next Generation CEI-448G Framework document project [liaison letter](#) and [attachment](#)

### External Liaison letters (new)

TIA TR42.11 Request for insight regarding MPO MDIs [liaison slides](#)

### External Liaison reports

TIA TR-42 Telecommunications Cabling Systems – Bob Voss

[https://www.ieee802.org/3/minutes/mar26/20260310\\_TIA\\_Liaison\\_Report\\_802.3.pdf](https://www.ieee802.org/3/minutes/mar26/20260310_TIA_Liaison_Report_802.3.pdf)

INCITS Fibre Channel – Tom Palkart

<https://www.ieee802.org/3/minutes/mar26/T11%20liaison%20report%20mar%202026.pdf>

### Opening reports:

IEEE 802.3 rules report – Adam Healey

[https://www.ieee802.org/3/minutes/mar26/0326\\_rules\\_open\\_report.pdf](https://www.ieee802.org/3/minutes/mar26/0326_rules_open_report.pdf)

IEEE 802.3 Maintenance - Adam Healey

[https://www.ieee802.org/3/minutes/mar26/0326\\_maint\\_open\\_report.pdf](https://www.ieee802.org/3/minutes/mar26/0326_maint_open_report.pdf)

Mr. Law asked if there was anyone that still hadn't signed into IMAT and that he would not be adjusting the attendance after the meeting, none responded.

IEEE P802.3da 10 Mb/s Single Pair Multidrop Segments Enhancement Task Force - Chad Jones

[https://www.ieee802.org/3/minutes/mar26/802d3da\\_task\\_force\\_open\\_report\\_0326.pdf](https://www.ieee802.org/3/minutes/mar26/802d3da_task_force_open_report_0326.pdf)

IEEE P802.3dg 100 Mb/s Long-Reach Single Pair Ethernet Task Force - George Zimmerman

[https://www.ieee802.org/3/minutes/mar26/802d3dg\\_open\\_report\\_Mar2026.pdf](https://www.ieee802.org/3/minutes/mar26/802d3dg_open_report_Mar2026.pdf)

IEEE P802.3dj 200 Gb/s, 400 Gb/s, 800 Gb/s, and 1.6 Tb/s Ethernet Task Force - John D'Ambrosia

[https://www.ieee802.org/3/minutes/mar26/2603\\_3dj\\_open\\_report.pdf](https://www.ieee802.org/3/minutes/mar26/2603_3dj_open_report.pdf)

IEEE P802.3dk Greater than 50 Gb/s Bidirectional Optical Access PHYs Task Force -Yuanqiu Luo

[https://www.ieee802.org/3/minutes/mar26/802d3dk\\_Task\\_Force\\_open\\_report\\_2026MarPlenary.pdf](https://www.ieee802.org/3/minutes/mar26/802d3dk_Task_Force_open_report_2026MarPlenary.pdf)

IEEE P802.3dm Asymmetrical Electrical Automotive Ethernet Task Force – Natalie Wienckowski

[https://www.ieee802.org/3/minutes/mar26/802d3dm\\_TF\\_open\\_report.pdf](https://www.ieee802.org/3/minutes/mar26/802d3dm_TF_open_report.pdf)

IEEE P802.3dp Cabling RestrPDTions for Single Pair Power over Ethernet Task Force – Chad Jones

[https://www.ieee802.org/3/minutes/mar26/802d3dp\\_task\\_force\\_open\\_report\\_0326.pdf](https://www.ieee802.org/3/minutes/mar26/802d3dp_task_force_open_report_0326.pdf)

IEEE P802.3dq Pin-Optimized PHY Interface Task Force Report – Jason Potterf

[https://www.ieee802.org/3/minutes/mar26/POPI\\_Plenary\\_Opening\\_Report\\_2026-03-09.pdf](https://www.ieee802.org/3/minutes/mar26/POPI_Plenary_Opening_Report_2026-03-09.pdf)

IEEE P802.3-2022/Cor 2 (IEEE 802.3dr) Optical Automotive Ethernet TDFOM – Luisma Torres

[https://www.ieee802.org/3/minutes/mar26/802d3dr\\_task\\_force\\_open\\_report\\_01\\_0326.pdf](https://www.ieee802.org/3/minutes/mar26/802d3dr_task_force_open_report_01_0326.pdf)

IEEE P802.3ds 200 Gb/s per wavelength Multimode Fibre (MMF) optical PHYs Task Force opening report – Mabud Choudhury

[https://www.ieee802.org/3/minutes/mar26/3ds\\_task\\_force\\_open\\_report\\_2603.pdf](https://www.ieee802.org/3/minutes/mar26/3ds_task_force_open_report_2603.pdf)

IEEE P802.3dt Ethernet Metadata Services Task Force opening report – David Ofelt

[https://www.ieee802.org/3/minutes/mar26/802d3dt\\_task\\_force\\_opening\\_report\\_20260309.pdf](https://www.ieee802.org/3/minutes/mar26/802d3dt_task_force_opening_report_20260309.pdf)

IEEE 802.3 New Ethernet Applications Ad Hoc – John D’Ambrosia

[https://www.ieee802.org/3/minutes/mar26/0326\\_NEA\\_open\\_report.pdf](https://www.ieee802.org/3/minutes/mar26/0326_NEA_open_report.pdf)

IEEE 802.3 Power Delivery Coordinating Committee Ad Hoc - Chad Jones

[https://www.ieee802.org/3/minutes/mar26/PDCC\\_adhoc\\_open\\_report\\_0326.pdf](https://www.ieee802.org/3/minutes/mar26/PDCC_adhoc_open_report_0326.pdf)

IEEE 802.3 Channel Operating margin (COM) opening report – Howard Heck

[https://www.ieee802.org/3/minutes/mar26/0326\\_COM\\_ad\\_hoc\\_open\\_report.pdf](https://www.ieee802.org/3/minutes/mar26/0326_COM_ad_hoc_open_report.pdf)

IEEE 802.3 YANG Ad Hoc – Peter Jones

[https://www.ieee802.org/3/minutes/mar26/802d3\\_yang\\_os\\_adhoc\\_opening\\_report\\_030926.pdf](https://www.ieee802.org/3/minutes/mar26/802d3_yang_os_adhoc_opening_report_030926.pdf)

400 Gbps per lane PHYs and Interfaces CFI opening report – Kent Lusted

[https://www.ieee802.org/3/minutes/mar26/2603\\_400GL\\_plenary\\_opening\\_report\\_v1\\_template.pdf](https://www.ieee802.org/3/minutes/mar26/2603_400GL_plenary_opening_report_v1_template.pdf)

Fault-Managed Power Ethernet powering techniques CFI opening report – Chad Jones

[https://www.ieee802.org/3/minutes/mar26/FMP\\_CFI\\_opening\\_report\\_0326.pdf](https://www.ieee802.org/3/minutes/mar26/FMP_CFI_opening_report_0326.pdf)

Room assignments and Subgroup schedules. Mr. Jones shared how to find the meeting room locations for the week and gave the location on the website for the online schedule.

Mr. Law announced that as the agenda had been exhausted the meeting was adjourned.

Mr. Law adjourned the meeting at 12:14 PDT.

Adjourned.

## UNAPPROVED MINUTES

### IEEE 802.3 Ethernet Working Group

#### Plenary Closing Meeting

12-Mar 2026

<https://www.ieee802.org/3/minutes/mar26/index.html>

**THURSDAY, 12-MAR 2026**

Minutes were taken by IEEE 802.3 Ethernet Working Group Secretary Jon Lewis.

#### ADMINISTRATIVE MATTERS

##### Call to order

David Law, Chair of the IEEE 802.3 Ethernet Working Group, called the meeting to order at 13:15 PDT.

[https://www.ieee802.org/3/minutes/mar26/0326\\_802\\_3\\_closing\\_plenary.pdf](https://www.ieee802.org/3/minutes/mar26/0326_802_3_closing_plenary.pdf)

##### Welcome, introductions, and general announcements

Mr. Law noted that it would be too time consuming to have each individual introduce themselves, that introductions would not be done at this hybrid meeting.

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## Review and approval of agenda

Mr. Law noted that a soft copy of the draft agenda had been posted to the minutes section for this meeting.

Mr. Law asked if there were any additions to the draft agenda. There was no response.

### **MOTION #1**

Approve the agenda modifying the posted agenda as posted.

M: John D'Ambrosia

S: Kent Lusted

Procedural (> 50%)

Motion Passed by unanimous consent 12-Mar 2026, 13:25 PDT

## Call for patents

Please see

[https://www.ieee802.org/3/minutes/mar26/0326\\_802\\_3\\_closing\\_plenary.pdf#page=11](https://www.ieee802.org/3/minutes/mar26/0326_802_3_closing_plenary.pdf#page=11)

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- Prior to presentation or submission, you shall notify the Working Group Chair of previously Published material and should assist the Chair in obtaining copyright permission acceptable to IEEE SA. For material that is not previously Published, IEEE is automatically granted a license to use any material that is presented or submitted.

Mr. Law reviewed the Code of Conduct and Code of Ethics at the request of a participant.

Mr. Law reviewed the IEEE SA participation slides.

[https://www.ieee802.org/3/minutes/mar26/0326\\_802\\_3\\_closing\\_plenary.pdf#page=19](https://www.ieee802.org/3/minutes/mar26/0326_802_3_closing_plenary.pdf#page=19)

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Mr. Law provided details on specifying your employer and affiliation during IEEE-SA "individual process" meetings.

[https://www.ieee802.org/3/minutes/mar26/0326\\_802\\_3\\_closing\\_plenary.pdf#page=21](https://www.ieee802.org/3/minutes/mar26/0326_802_3_closing_plenary.pdf#page=21)

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- Participants shall comply with IEEE SA Standards Board Operations Manual 5.1.4 Standards promotion and social media communication requirements.
- Participants can contact the IEEE concerning alleged violations of IEEE's Code of Conduct, Code of Ethics, or other policies and rules using the information given.

## General Working Group business

### Attendance procedures, tool, and e-mail list maintenance

Mr. Law explained the membership requirements (gaining):

- Attendance in at least 75% of meeting slots<sup>2</sup> at 2 of last 4 plenary sessions
  - Attendance in at least 75% of meeting slots at a recent IEEE 802.3 Ethernet Working Group or Task Group Interim Session may be substituted for one of the two plenary sessions
- Attendance in at least 75% of meeting slot's duration is required for that attendance to count towards gaining or maintaining voting membership
- Provide valid contact information
- Provide declaration of affiliation
- Request to become member during potential voter agenda item at an IEEE 802.3 Ethernet Working Group opening or closing **plenary** meeting

Membership requirements (retaining)

- Continue to meet the above attendance, contact, and affiliation requirements
- Participate in two out of the last three Working Group Letter Ballot Series

Mr. Law noted the meeting this plenary meeting requires a paid registration fee and that attending any of the sessions without paying the fee had adverse consequences.

### Membership and attendance recording

Mr. Lewis reviewed the membership and attendance tool procedures.

[https://www.ieee802.org/3/minutes/mar26/0326\\_802\\_3\\_closing\\_plenary.pdf#page=27](https://www.ieee802.org/3/minutes/mar26/0326_802_3_closing_plenary.pdf#page=27)

Please see <http://ieee802.org/3/rules/index.html> for complete information.

### Review of voting membership

Please [https://www.ieee802.org/3/minutes/mar26/0326\\_voters.pdf](https://www.ieee802.org/3/minutes/mar26/0326_voters.pdf)

### Review of voters in peril

Please [https://www.ieee802.org/3/minutes/mar26/0326\\_peril.pdf](https://www.ieee802.org/3/minutes/mar26/0326_peril.pdf)

### Review of Potential voters

Please see [https://www.ieee802.org/3/minutes/mar26/0326\\_potential.pdf](https://www.ieee802.org/3/minutes/mar26/0326_potential.pdf)

The following participants requested voting rights during the closing plenary:

Zhang, Tingting

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<sup>2</sup> There are four IMAT meeting slots during the day during plenary and credited interim sessions

## IEEE 802 LAN/MAN Standards Committee items

Mr. Law showed the IEEE 802 LMSC report.

[https://www.ieee802.org/3/minutes/mar26/0326\\_802\\_3\\_closing\\_plenary.pdf#page=30](https://www.ieee802.org/3/minutes/mar26/0326_802_3_closing_plenary.pdf#page=30)

Mr. Jones gave a brief update on future meetings.

Mr. Law reviewed the IEEE 802.3 Working Group Proposed election procedures for the March 2026 elections.

[https://www.ieee802.org/3/minutes/mar26/0326\\_802\\_3\\_closing\\_plenary.pdf#page=31](https://www.ieee802.org/3/minutes/mar26/0326_802_3_closing_plenary.pdf#page=31)

### **Election of Working Group Chair**

David Law for Working Group Chair

Y: 125 N: 2 A: 5 (NOTE: One “Yes” vote recorded manually)

12-Mar 2026, 14:01 PDT

### **Election of Working Group Vice-Chair**

Adam Healey for Working Group Vice-Chair

Y: 129 N: 0 A: 1 (NOTE: One “Yes” vote recorded manually)

12-Mar 2026, 14:07 PDT

## Other IEEE 802 PARs

Mr. Lusted noted that there were no PARs to comment on at this plenary session.

## **Liaisons**

### **External Liaison letters (old)**

ITU-T SG15 Updates to ANT and HNT Standards Overviews and Work Plans [liaison letter](#)

ITU-T SG15 Update to OTNT Standards Overview and Work Plan [liaison letter](#) and [attachment](#)

ITU-T SG15 Development of weakly-coupled multi-core fibre Recommendations [liaison letter](#)

ITU-T SG15 Approval of Technical Report on International Optical Networks towards 2030 (ION-2030) and Beyond [liaison letter](#) and [attachment](#)

ITU-T SG15 Technical report of use cases and requirements beyond 10Gbps [liaison letter](#)

OIF: Next Generation CEI-448G Framework document project [liaison letter](#) and [attachment](#)

## External Liaison letters (new)

TIA TR42.11 Request for insight regarding MPO MDIs [liaison slides](#)

Mr. Law reminded attendees to log their attendance in IMAT. He asked if there was anyone that was unable to sign into IMAT or had issues in registering attendance. There was no response.

### Joint IEEE 802 / ITU-T SG15 Workshop

Mr. D'Ambrosia notified the group of a planned joint workshop.

[https://www.ieee802.org/3/minutes/mar26/dambrosia\\_wg\\_2603.pdf](https://www.ieee802.org/3/minutes/mar26/dambrosia_wg_2603.pdf)

### Future Meetings Report – Chad Jones

[https://www.ieee802.org/3/minutes/mar26/0326\\_802d3\\_future\\_meetings.pdf](https://www.ieee802.org/3/minutes/mar26/0326_802d3_future_meetings.pdf)

Future Meetings Straw Poll:

How many people would like to come back to this venue?

Yes: 76      No: 1

Did you go to the social?

Yes: 66      No: 13

If you attended the social, did you like the social?

Yes: 56      No: 6

IEEE 802.3 September 2027 Offer to Host – Tom Palkart

<https://www.ieee802.org/3/minutes/mar26/IEEE-8023%20September%20Samtec-2027-Interim.pdf>

Straw Poll:

Accept the September 2027 offer to host by Samtec for Vancouver, WA

Yes: 82      No: 55

IEEE 802.3 January 2028 Offer to Host – Chad Jones

<https://www.ieee802.org/3/minutes/mar26/IEEE-8023-January-2028-Interim-Offer-to-Host-by-Eridu.pdf>

**MOTION #2**

Move that IEEE 802.3 accept the Eridu offer to host the January 2028 interim as detailed in:

<https://www.ieee802.org/3/minutes/mar26/IEEE-8023-January-2028-Interim-Offer-to-Host-by-Eridu.pdf>

M: Chad Jones            S: George Zimmerman

By Rule  $\geq$  75%

Y: 90 N: 19 A: 16

Motion Passed 12-Mar 2026, 15:03 PDT

**Closing reports and actions:**

IEEE 802.3 Rules - Adam Healey

[https://www.ieee802.org/3/minutes/mar26/0326\\_rules\\_close\\_report.pdf](https://www.ieee802.org/3/minutes/mar26/0326_rules_close_report.pdf)

**MOTION #3**

Approve the proposed IEEE 802.3 rules change 1-11/25 without a 30-day WG letter ballot.

M: A. Healey            S: George Zimmerman

By Rule  $\geq$  75%

Motion Passed by unanimous consent 12-Mar 2026, 15:10 PDT

IEEE P802.3dg 100 Mb/s Long-Reach Single Pair Ethernet Task Force - George Zimmerman  
[https://www.ieee802.org/3/minutes/mar26/802d3dg\\_close\\_report\\_Mar2026.pdf](https://www.ieee802.org/3/minutes/mar26/802d3dg_close_report_Mar2026.pdf)

**MOTION #4**

Move that the IEEE 802.3 Working Group affirm the CSD responses in <https://mentor.ieee.org/802-ec/dcn/22/ec-22-0086-00-ACSD-p802-3dg.pdf> and request conditional approval to progress the IEEE P802.3dg draft to RevCom once the IEEE Standards Association ballot process has been successfully completed.

M: George Zimmerman S: Chad Jones

Technical  $\geq$  75%

Y: 105 N: 0 A: 8

Motion Passed 12-Mar 2026, 15:15 PDT

The Group took a short break at 15:16

The Working Group meeting resumes at 15:30

IEEE P802.3dj 200 Gb/s, 400 Gb/s, 800 Gb/s, and 1.6 Tb/s Ethernet Task Force closing report – John D’Ambrosia

[https://www.ieee802.org/3/minutes/mar26/2603\\_3dj\\_closed\\_report.pdf](https://www.ieee802.org/3/minutes/mar26/2603_3dj_closed_report.pdf)

**MOTION #5**

Move that the IEEE 802.3 Working Group approve:  
IEEE\_802d3\_to\_UEC\_OIF\_UALink\_ITU\_INCITS\_3djD3p0\_2603\_draft\_Redacted.pdf  
with editorial license granted to the Chair (or his appointed agent) as a liaison communication from the IEEE 802.3 to UEC, OIF, UALink, ITU-T & INCITS

M: John D’Ambrosia

S: Tom Huber

Technical ( $\geq$ 75%)

Y: 75 N: 0 A: 2

Motion Passed 12-Mar 2026, 15:39 PDT

IEEE P802.3dk Greater than 50 Gb/s Bidirectional Optical Access PHYs Task Force -Yuanqiu Luo  
[https://www.ieee802.org/3/minutes/mar26/802d3dk\\_Task\\_Force\\_close\\_report\\_2026MarPlenary.pdf](https://www.ieee802.org/3/minutes/mar26/802d3dk_Task_Force_close_report_2026MarPlenary.pdf)

**MOTION #6**

Move that the IEEE 802.3 Working Group re-affirm the CSD responses in  
<https://mentor.ieee.org/802-ec/dcn/22/ec-22-0268-00-ACSD-ieee-p802-3dk.pdf>  
and request approval to submit the IEEE P802.3dk draft to RevCom.

M: Yuanqiu Luo

S: Kenneth Jackson

Technical ( $\geq 75\%$ )

Y: 82 N: 0 A: 7

Motion Passed 12-Mar 2026, 15:42 PDT

IEEE P802.3dm Asymmetrical Electrical Automotive Ethernet – Natalie Wienckowski  
[https://www.ieee802.org/3/minutes/mar26/802d3dm\\_TF\\_close\\_report.pdf](https://www.ieee802.org/3/minutes/mar26/802d3dm_TF_close_report.pdf)

**MOTION #7**

Move that the IEEE 802.3 Working Group approve the new set of objectives adopted by  
the Task Force this week  
[https://www.ieee802.org/3/dm/public/0326/Objectives\\_ISAAC\\_01\\_0326.pdf](https://www.ieee802.org/3/dm/public/0326/Objectives_ISAAC_01_0326.pdf).

M: N. Wienckowski on behalf of the Task Force

Technical ( $\geq 75\%$ )

Motion Passed by unanimous consent 12-Mar 2026, 15:51 PDT

IEEE P802.3dq Pin-Optimized PHY Interface Task Force – Jason Potterf  
[https://www.ieee802.org/3/minutes/mar26/POPI\\_Plenary\\_Closing\\_Report\\_2026-03-12\\_v01.pdf](https://www.ieee802.org/3/minutes/mar26/POPI_Plenary_Closing_Report_2026-03-12_v01.pdf)

IEEE Std 802.3-2022/Cor 2 (IEEE 802.3dr) – Luisma Torres  
[https://www.ieee802.org/3/minutes/mar26/802d3dr\\_task\\_force\\_closing\\_report\\_01\\_0326.pdf](https://www.ieee802.org/3/minutes/mar26/802d3dr_task_force_closing_report_01_0326.pdf)



IEEE 802.3 New Ethernet Applications ad hoc E4AI Assessment – John D’Ambrosia

[https://www.ieee802.org/3/minutes/mar26/JD\\_2603\\_e4ai\\_close\\_report.pdf](https://www.ieee802.org/3/minutes/mar26/JD_2603_e4ai_close_report.pdf)

Mr. D’Ambrosia noted that we would review the liaison letter later in the meeting.

**MOTION #11**

Move that the IEEE 802.3 Working Group approve the delegation of Kent Lusted, David Ofelt, and Mabud Choudhury, as IEEE 802.3 representatives from the IEEE 802.3 Working Group to Open Compute Project / ESUN for the 09 April 2026 meeting (tentative) and any subsequent meetings related to current or emerging IEEE 802.3 efforts addressing Ethernet solutions for AI.

M: John D’Ambrosia

S: Kent Lusted

Technical ( $\geq 75\%$ )

Motion Passed by unanimous consent 12-Mar 2026, 16:38 PDT

IEEE 802.3 Power Delivery Coordinating Committee ad hoc scope update – David Law

[https://www.ieee802.org/3/minutes/mar26/0326\\_802\\_3\\_closing\\_plenary.pdf#page=42](https://www.ieee802.org/3/minutes/mar26/0326_802_3_closing_plenary.pdf#page=42)

IEEE 802.3 COM Ad Hoc – Howard Heck

[https://www.ieee802.org/3/minutes/nov25/1125\\_COM\\_ad\\_hoc\\_closing\\_report.pdf](https://www.ieee802.org/3/minutes/nov25/1125_COM_ad_hoc_closing_report.pdf)

**MOTION #12**

Move to generate COM v4.14 from COM 4.13 and the dispositions per 0326\_COM\_ad\_hoc\_plenary\_close\_report, slide 3.

M: Kent Lusted

S: Rich Mellitz

Technical ( $\geq 75\%$ )

Motion Passed by unanimous consent 12-Mar 2026, 16:51 PDT

Mr. D’Ambrosia continued reviewing the liaison letter to ITU-T from the E4AI assessment.

**MOTION #13**

Move that the IEEE 802.3 Working Group approve:

IEEE\_802d3\_to\_ITU\_e4ai\_2603\_draft\_Redacted.pdf

with editorial license granted to the Chair (or his appointed agent) as liaison communications from the IEEE 802.3 Working Group to ITU

M: John D'Ambrosia

S: Tom Huber

Technical ( $\geq 75\%$ )

Y: 74 N: 0 A: 6

Motion Passed 12-Mar 2026, 16:56 PDT

IEEE 802.3 YANG Open Source Ad Hoc – Peter Jones

[https://www.ieee802.org/3/minutes/nov25/802d3\\_yang\\_os\\_adhoc\\_closing\\_report\\_b\\_111325.pdf](https://www.ieee802.org/3/minutes/nov25/802d3_yang_os_adhoc_closing_report_b_111325.pdf)

IEEE 802.3 400 Gbps per lane PHYs and Interfaces CFI – Kent Lusted

[https://www.ieee802.org/3/minutes/mar26/2603\\_400GL\\_plenary\\_closing\\_report\\_v1\\_template.pdf](https://www.ieee802.org/3/minutes/mar26/2603_400GL_plenary_closing_report_v1_template.pdf)

**MOTION #14**

Move that the IEEE 802.3 Working Group request the formation of a Study Group to develop a Project Authorization Request (PAR) and Criteria for Standards Development (CSD) for Physical Layer specifications supporting existing Ethernet rates using 400 Gbps-per-lane signaling for electrical interconnects as well as SMF optical interconnects with reaches of up to 500 meters

M: Kent Lusted

S: Mark Nowell

> 50% by Rule

Y: 88 N: 0 A: 1

Motion Passed 12-Mar 2026, 17:05 PDT

**MOTION #15**

Move that the IEEE 802.3 Working Group request the formation of a Study Group to develop a Project Authorization Request (PAR) and Criteria for Standards Development (CSD) for Physical Layer specifications supporting existing Ethernet rates using 400 Gbps-per-lane signaling for electrical interconnects as well as SMF optical interconnects with reaches of up to 500 meters

M: Kent Lusted

S: Mark Nowell

Technical ( $\geq 75\%$ )

Y: 85 N: 0 A: 6

Motion Passed 12-Mar 2026, 17:11 PDT

Mr. Law announced that should the 400Gb/s/lane PHYs and interfaces Study Group be approved he would appoint Kent Lusted Chair.

IEEE 802.3 Fault Managed Power Ethernet Powering Techniques CFI – Chad Jones

[https://www.ieee802.org/3/minutes/mar26/FMP\\_CFI\\_CLOSE\\_0326.pdf](https://www.ieee802.org/3/minutes/mar26/FMP_CFI_CLOSE_0326.pdf)

**MOTION #16**

Move that the IEEE 802.3 Working Group request the formation of a Study Group to develop a Project Authorization Request (PAR) and Criteria for Standards Development (CSD) responses for Fault Managed Power Ethernet powering techniques.

M: Chad Jones

S: John D'Ambrosia

Technical ( $\geq 75\%$ )

Y: 85 N: 0 A: 4

Motion Passed 12-Mar 2026, 17:20 PDT

Mr. Law announced that should the Fault-Managed Power Ethernet powering techniques Study Group be approved he would appoint Bob Voss Chair.

**Awards:**

IEEE P802.3da 10 Mb/s Single Pair Multidrop Segments Enhancements – Chad Jones

Mr. Law asked if there was any additional general business:

Mr. Law announced that as the agenda had been exhausted the meeting was adjourned.

Mr. Law adjourned the meeting at 17:29 PDT.

Adjourned.

Appendix A: Attendance list for Working Group Opening plenary from IMAT

<b>Name</b>	<b>Employer</b>	<b>Affiliation</b>
Abraham, Shiju		Acsia Technologies
Abramczyk, Jaroslaw		Coherent
Ahuja, Ramanjit	ON Semiconductor	ON Semiconductor
Akinwale, Oluwafemi	Intel Corporation	Intel Corporation
Alloin, Laurent		Ciena Corporation
Ancel, Patrice		BMW AG
Aripirala, Ravi		Texas Instruments (India) Pvt. Ltd.; Texas Instruments Inc.
Aronson, Joseph	Texas Instruments Inc.	Texas Instruments Inc.
Baggett, Tim	Microchip Technology, Inc.	Microchip Technology, Inc.
Bar-Niv, Amir	Aquantia Corp	Marvell
Benyamin, Saied	Ethernovia	Ethernovia
Bernier, Eric	Huawei Technologies Canada Co., Ltd.	Huawei Technologies Canada Co., Ltd.
Boyer, Rich	Aptiv - Signal and Power Solutions	Aptiv Signal and Power Solutions
Brown, Matthew	Alphawave Semi	Qualcomm
Bruckman, Leon	NVIDIA	NVIDIA
Brychta, Michal	Analog Devices Inc.	Analog Devices Inc.
Buckmeier, Brian	Belfuse INC	Bel Stewart Connector
Budweiser, Karl		BMW AG; BMW Group
Calvin, John	Keysight Technologies	Keysight Technologies
Castro, Jose	Panduit	Panduit Corp.
Chan, Jason		Arista Networks
Chang, Jae-yong	Keysight Technologies Inc	Keysight Technologies Inc
Chang, Yongmao	Inphi Corporation	Source Photonics
Chen, Chan	Self Employed	Independent/AOI
Chen, Lihao	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
cheng, xiaoyue		Infineon Technologies
Chidambaram, Valliaappan		Acsia Technologies
Chimento, Nicholas		Analog Devices Inc.
Chini, Ahmad	Broadcom Corporation	Broadcom Corporation
Choudhury, Golam	Genuine Optics	Genuine Optics
Clay, Richard	Magnolia Electronics	Magnolia Electronics
Cole, Christopher R	Finisar Corporation	Coherent Corp.
Cordaro, Jay	Analog Devices	Analog Devices
Cox, Ian		Broadcom Corporation
Dai, Shaoan		Infineon Technologies
Dalmia, Kamal	Aviva Links Inc	NXP Semiconductors
D'Ambrosia, John	Futurewei Technologies, U.S. Subsidiary of Huawei	Futurewei Technologies, U.S. Subsidiary of Huawei
Dawe, Piers J G	NVIDIA	Nvidia
de Koos, Andras	Microchip Technology Inc	Microchip Technology Inc
Djahanshahi, Hormoz	Microchip Technology, Inc.	Microchip Technology, Inc.

<b>Name</b>	<b>Employer</b>	<b>Affiliation</b>
Dsilva, Hansel		Amphenol Corporation
Dudek, Michael	Marvell	Marvell
Edele, Jonas		BMW AG; BMW Group
Elangovan, Vivekanandh	Infineon Technologies	Infineon Technologies
El-Chayeb, Ahmad	Keysight Technologies Inc	Keysight Technologies Inc
Enoki, Naomichi		Murata Electronics
Estrakh, Daniel	Valens Semiconductor	Valens Semiconductor
Fan, Xiaojie	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Ferretti, Vincent	Corning Incorporated	Corning Incorporated
Fuller, Paul		Infineon Technologies
Galan, Jose	MaxLinear, Inc.	MaxLinear, Inc.
Gauthier, Claude	NXP Semiconductors	NXP Semiconductors
Geng, Limin	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
George, John	Lightera	Lightera
Ghiasi, Ali	Ghiasi Quantum LLC	Ghiasi Quantum LLC; Marvell Semiconductor, Inc.
Goel, Sachin	Aviva Links Inc	NXP
Goergen, Joel	Cisco Systems, Inc.	Cisco Systems, Inc.
Gorshe, Steven Scott	Microchip Technology, Inc.	Microchip Technology, Inc.
Goto, Hideki	Toyota Motor Corporation	Toyota Motor Corporation
Graba, James	Broadcom Corporation	Broadcom Corporation
Graber, Steffen	Pepperl+Fuchs SE	Pepperl+Fuchs SE
Gupta, Ajeya		General Motors Company
Hameed, Anil		Acsia Technologies
HE, MICHAEL	TeraHop Pte. Ltd.	TeraHop Pte. Ltd.
He, Xiang	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Healey, Adam	Broadcom Inc.	Broadcom Inc.
Heck, Howard	TE Connectivity	TE Connectivity
Hidaka, Yasuo	Credo Semiconductor	Credo Semiconductor
Hiroaki, Kukita	Yamaichi Electronics	Yamaichi Electronics
Hogenmueller, Thomas	Robert Bosch GmbH	Robert Bosch GmbH
Hong, Paul	MaxLinear, Inc.	MaxLinear, Inc
Houck, TJ	Infineon Technologies	Infineon Technologies
Hu, Runlong		China Mobile Communications Group Co.,Ltd; China Mobile Communications Group Co.,Ltd
Huang, Kechao	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
HUANG, QINHUI	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Huber, Thomas	Nokia	Nokia
Hutchison, Guy	Aviva Links	Aviva Links Inc; Aviva Links Inc.
HYAKUTAKE, YASUHIRO	Orbray Co., Ltd.	Orbray Co., Ltd.
Isono, Hideki	Furukawa FITEL Optical Components Limited	Furukawa FITEL Optical Components
Issenhuth, Tom	Issenhuth Consulting, LLC	Huawei Technologies Co., Ltd

<b>Name</b>	<b>Employer</b>	<b>Affiliation</b>
Iwasaki, Yutaka	Hirose Electric Co.,Ltd.	Hirose Electric Co., Ltd.
Jackson, Kenneth	Sumitomo Electric Industries, LTD	Sumitomo Electric Industries, LTD
Jeffreis, Brad		Analog Devices Inc.
Jin, Robert	Montage Technology, Inc	Montage Technology
Jochim, Markus	General Motors Company	General Motors Company
Johnson, John	Broadcom Corporation	Broadcom Corporation
Jones, Chad	Cisco Systems, Inc.	Cisco Systems, Inc.
Jones, Peter	Cisco Systems, Inc.	Cisco Systems, Inc.
Jonsson, Ragnar	Marvell Semiconductor, Inc.	Marvell
Joseph, Gloria		Acsia Technologies
Kagami, Manabu	Nagoya Institute of Technology	Nagoya Institute of Technology (NITech)
Kandarpa, Venkata	Chelsio Communications	NXP Semiconductors
Kapoor, Samay	Aviva Links	Aviva Links Inc.
Kareti, Upen	Cisco Systems, Inc.	Cisco Systems, Inc.
KATO, TAKAHIRO		Dexerials
Kiessling, Marcel	Beckhoff Automation	Beckhoff Automation
Kim, Do Kyun	LG ELECTRONICS	LG ELECTRONICS
Kim, Gyudong	Analog Devices Inc.	Analog Devices Inc.
Kim, Yongbum	General Motors Company	General Motors Company
Kimber, Eric	Semtech Ltd	Semtech Ltd
Kleinwaechter, Mathias	in-tech GmbH	in-tech GmbH
Kochuparambil, Elizabeth	Cisco Systems, Inc.	Cisco Systems, Inc.
Kocsis, Sam	Amphenol Corporation	Amphenol Corporation
Kondo, Taiji	Dexerials Corporation	Dexerials Corporation
Kota, Kishore	Marvell Semiconductor, Inc.	Marvell Semiconductor, Inc.
Lackner, Hans	QoSCom GmbH	QoSCom GmbH
Landry, Gary	Texas Instruments Inc.	Texas Instruments Inc.
Lasry, Ariel	Qualcomm Technologies, Inc	Qualcomm Technologies, Inc
Law, David	Hewlett Packard Enterprise	Hewlett Packard Enterprise
Lee, Ching-Yen		Realtek Semiconductor Corp.
Lee, Dongjae		Newracom Inc.
Lee, Sylvanus	Leviton Manufacturing Co.	Leviton Manufacturing Co.
Lessard, Stephane	Ericsson AB	Ericsson AB
Lewis, David	SPECIPHY / Lumentum	SPECIPHY, LUMENTUM
Lewis, Jon	Dell Technologies	Dell Technologies
Li, jiaqi		Huawei Technologies Co., Ltd
Li, Mike-Peng	Altera Corporation	Advanced Micro Devices (AMD)
Li, Pei-Rong	MediaTek Inc.	MediaTek Inc.
Lim, Hoei	NXP Semiconductors	NXP Semiconductors
Lim, Jane	Cisco Systems, Inc.	Cisco Systems, Inc.
Lin, YK		Realtek Semiconductor Corp.
Lin, Youxi	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd

<b>Name</b>	<b>Employer</b>	<b>Affiliation</b>
Little, Terrance	Foxconn Electronics Inc.	Foxconn Electronics Inc.
Liu, Cathy	Broadcom Corporation	Broadcom Corporation
Lo, William	Axonne Inc.	Axonne Inc.
Lou, Wei		Broadcom Corporation
lu, chao	BMW Group	BMW Group
Luo, Yuanqiu	Futurewei Technologies	Futurewei Technologies
Lusted, Kent	Synopsys, Inc.	Synopsys, Inc.
Lyu, Yunping(Lily)	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Maguire, Valerie	Copperopolis	Copperopolis (aff'l with CME Consulting, Microchip, and NXP)
Maki, Jeffery	Hewlett Packard Enterprise	Hewlett Packard Enterprise
Mammenga, Kevin		Wilder Technologies
Maniloff, Eric	Ciena Corporation	Ciena Corporation
Mark, Simon	Würth Elektronik Group	Würth Elektronik Group
Marques, Flavio	Lightera	Lightera
Martino, Kjersti	Inneos	Inneos
Mascitto, Marco	Infinera Canada Inc.	Nokia
Matuz, Balazs		Huawei Technologies Duesseldorf GmbH
McClellan, Brett	Marvell Semiconductor, Inc.	Marvell Semiconductor, Inc.
Mellitz, Richard	Samtec, Inc.	Samtec, Inc.
Messica, Barak		NVIDIA
mi, guangcan	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Miskho, Michael		Analog Devices Inc.
Moorwood, Charles	Keysight Technologies	Keysight Technologies
Muhigana, Ernest	MACOM Technology Solutions Holdings, Inc.	Macom Technology Solutions Inc
Muller, Shimon	Enfabrica Corp.	Enfabrica
Muma, Scott	Microchip Technology, Inc.	Microchip Technology, Inc.
MURAKAMI, YUKI	1Finity	1Finity
Murray, Brian	Analog Devices Inc.	Analog Devices Inc.
Murty, Ramana	Broadcom Inc.	Broadcom Corporation
Muth, Karlheinz	Broadcom Corporation	Broadcom Corporation
Nagaraja, Srikanth		Texas Instruments (India) Pvt. Ltd.; Texas Instruments Inc.
Nakamoto, Edward	Spirent Communications	VIAVI Solutions
Nering, Raymond	Cisco Systems, Inc.	Cisco Systems, Inc.
Ng, Hiok Tiaq	NXP Semiconductors	NXP Semiconductors
Nicholl, Gary	Cisco Systems, Inc.	Cisco Systems, Inc.
Nicholl, Shawn	Advanced Micro Devices (AMD)	Advanced Micro Devices (AMD)
NIIHARA, YOSHIHIRO	Fujikura Ltd.	Fujikura Ltd.
Ninomiya, Tiger	Accelink USA Corporation	Accelink USA Corporation
Nowell, Mark	Cisco Systems, Inc.	Cisco Systems, Inc.
Ofelt, David	Hewlett Packard Enterprise	Hewlett Packard Enterprise

<b>Name</b>	<b>Employer</b>	<b>Affiliation</b>
Omori, Kumi	NEC Corporation	NEC Corporation
Opsasnick, Eugene	Broadcom Inc.	Broadcom Inc.
Osorio, Luz		Nokia
Pal, Debajyoti		ON Semiconductor
Palkert, Thomas	Samtec, Inc.	Samtec, Inc.
Pan, Chunpo		Broadcom Corporation
Pandey, Sujan	Velinktech	Velinktech
Park, Pusik		Korea Electronics Technology Institute (KETI);
Parkholm, Ulf	Telefon AB LM Ericsson	Ericsson AB
Parthasarathy, Vasu	Broadcom Corporation	Broadcom Corporation
Peng, BC		MediaTek Inc.
Pepper, Gerald	Keysight Technologies	Keysight Technologies
Phadke, Rohan	Arista Networks	Arista Networks
Potterf, Jason	Cisco Systems, Inc.	Cisco Systems, Inc.
Quan, Yu	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Rabinovich, Rick	Keysight Technologies	Keysight Technologies
Rajagopal, Karthik	Texas Instruments Inc.	Texas Instruments Inc.
Ran, Adee	Cisco Systems, Inc.	Cisco Systems, Inc.
Ransford, Michael		Corning Incorporated
Razavi, Alireza	Marvell	Infineon Technologies
Reinhard, Michael	SEI Automotive Europe GmbH	SEI Automotive Europe GmbH
Ren, Hao	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Rodes, Roberto	II-VI	II-VI
Royer, Tyler	SENKO Advanced Components	SENKO Advanced Components
Rysin, Alexander	NVIDIA	NVIDIA
Sakai, Toshiaki	Socionext Inc.	socionext
Savi, Olindo	Hubbell Incorporated	Hubbell Incorporated
Schedl, Anton	BMW Group	BMW Group
Sedarat, Hossein	Ethernovia	Ethernovia
Sekel, Steve	Wilder Technologies	wilder Technologeis
Sharma, Rohit		Molex Incorporated
She, Qingya	Fujitsu Network Communications	1FINITY
Shiino, Masato	FURUKAWA ELECTRIC	FURUKAWA ELECTRIC
Sikkink, Mark	Hewlett Packard Enterprise	Hewlett Packard Enterprise
Simms, William	NVIDIA Corporation	NVIDIA Corporation
Sommers, Scott	Molex LLC	Molex Incorporated
Son, Yung Sung	Optomind Inc	Optomind Inc
Spruit, Hans	TRUMPF	Western Digital Corporation
Srivastava, Atul	NEL-America	NTT Electronics
Stephens, Jeremy	Advanced Micro Devices (AMD)	Advanced Micro Devices (AMD)
Strohmeier, Heiko	Robert Bosch GmbH	Robert Bosch GmbH
Sun, jingcong	Motorcomm Electronic Technology Co	Motorcomm Electronic Technology Co

<b>Name</b>	<b>Employer</b>	<b>Affiliation</b>
Sun, Yi	Lightera	Lightera
Swenson, Norman	Norman Swenson Consulting	Norman Swenson Consulting; Point2 Technology Inc.; Nokia
TAKAHARA, TOMOO	FUJITSU LABORATORIES LIMITED	1FINITY
TAKEUCHI, JUNICHI	JAE Electronics, Inc	JAE Electronics, Inc.
Tan, Yuxuan	Motorcomm	Motorcomm
Tanc, Ahmet		NXP Semiconductors; NXP Semiconductors
Tanz, Simon		BMW AG; BMW Group
TAZEBAY, MEHMET	Broadcom Corporation	Broadcom Corporation
Theodoras, James	Scintil Photonics	Scintil Photonics
Thomas, Rajan		Acsia Technologies
Thompson, Geoffrey	GraCaSI S.A.	INDEPENDENT
Tooyserkani, Pirooz	Cisco Systems, Inc.	Cisco Systems, Inc.
Torres, Luisma	Knowledge Development for POF SL	KD
Tracy, Nathan	TE Connectivity	TE Connectivity
Tran, Viet	Keysight Technologies	Keysight Technologies
Tu, Mike	Broadcom Corporation	Broadcom Corporation
Turner, Max	Ethernovia	Ethernovia
Umar, Ashraf		Molex Incorporated
Vakilian, Kambiz	Broadcom Corporation	Broadcom Corporation
Vanderlaan, Paul	UL Solutions	Panduit Corp.
Veloso Cauce, Gumersindo	BMW Group	BMW AG; BMW Group
Venkataraman, Srinivas	Broadcom Corporation	Broadcom Corporation
Voss, Robert	Panduit Corp.	Panduit Corp.
Wang, Haojie	China Mobile Communications Corporation (CMCC)	China Mobile Communications Corporation (CMCC)
Wang, Ruoxu	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Wang, Shun-Sheng	Realtek Semiconductor Corp.	Realtek Semiconductor Corp.
wang, weilai	BMW Group	BMW AG; BMW Group
Wang, Xiaofeng	Qualcomm Incorporated	Qualcomm Incorporated
WANG, Xuebo	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Watanabe, Yojiro	Mitsubishi Electric US, Inc.	Mitsubishi Electric US, Inc.
Weaver, James	Arista Networks	Arista Networks
Wei, Terry		Analog Devices Inc.
Wienckowski, Natalie	IVN Solutions LLC	IVN Solutions LLC; Ethernovia
Wig, Timothy	Samtec, Inc.	Samtec, Inc.
Wingrove, Michael	Ciena Corporation	Ciena Corporation
Withey, James	Fluke Corporation	Fluke Corporation
Wu, Dance	Marvell Semiconductor, Inc.	Infineon Technologies
Wu, Peter	Marvell Semiconductor, Inc.	Marvell Semiconductor, Inc.
XU, LI	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
xu, wenxiong	HG Genuine	HGGenuine
Xu, Yu	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd

<b>Name</b>	<b>Employer</b>	<b>Affiliation</b>
Yamazaki, Kinya	APRESIA Systems	APRESIA Systems
Yang, Penglin	Hygon Information Technology Co., Ltd.,	Hygon Information Technology Co., Ltd.
Yin, Shuang		Google
Zerna, Conrad	Aviva Links Inc	NXP Semiconductors
ZHANG, KAN		China Mobile (Chengdu) Information and Telecommunication
Zhang, Tingting	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Zhang, Wei		Broadcom Corporation
Zhu, Keyi		HUAWEI
Zhuang, Yan	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Zimmerman, George	CME Consulting, Inc.	CME Consulting/Analog Devices, APL Group, Cisco, Infineon, OnSemi, Sony
Zivny, Pavel	MultiLane	MultiLane
Zou, Congshi	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd

Appendix B: Attendance list for Working Group Closing plenary from IMAT

<b>Name</b>	<b>Employer</b>	<b>Affiliation</b>
Abraham, Shiju		Acsia Technologies
Abramczyk, Jaroslaw		Coherent
Akinwale, Oluwafemi	Intel Corporation	Intel Corporation
Aripirala, Ravi		Texas Instruments (India) Pvt. Ltd.; Texas Instruments Inc.
Aronson, Joseph	Texas Instruments Inc.	Texas Instruments Inc.
Baggett, Tim	Microchip Technology, Inc.	Microchip Technology, Inc.
Bar-Niv, Amir	Aquantia Corp	Marvell
Benyamin, Saied	Ethernovia	Ethernovia
Bernier, Eric	Huawei Technologies Canada Co., Ltd.	Huawei Technologies Canada Co., Ltd.
Boyer, Rich	Aptiv - Signal and Power Solutions	Aptiv Signal and Power Solutions
Brillhart, Theodore	Fluke Corporation	Fluke Corporation
Brown, Matthew	Alphawave Semi	Qualcomm
Bruckman, Leon	NVIDIA	NVIDIA
Brychta, Michal	Analog Devices Inc.	Analog Devices Inc.
Budweiser, Karl		BMW AG; BMW Group
Calvin, John	Keysight Technologies	Keysight Technologies
Castro, Jose	Panduit	Panduit Corp.
Chan, Jason		Arista Networks
Chang, Jae-yong	Keysight Technologies Inc	Keysight Technologies Inc
Chang, Yongmao	Inphi Corporation	Source Photonics
Chen, Chan	Self Employed	Independent/AOI
cheng, xiaoyue		Infineon Technologies
Chimento, Nicholas		Analog Devices Inc.
Chini, Ahmad	Broadcom Corporation	Broadcom Corporation
Choudhury, Golam	Genuine Optics	Genuine Optics
Cole, Christopher R	Finisar Corporation	Coherent Corp.
Cordaro, Jay	Analog Devices	Analog Devices
Cox, Ian		Broadcom Corporation
Dai, Shaoan		Infineon Technologies
Dalmia, Kamal	Aviva Links Inc	NXP Semiconductors
D'Ambrosia, John	Futurewei Technologies, U.S. Subsidiary of Huawei	Futurewei Technologies, U.S. Subsidiary of Huawei
Dawe, Piers J G	NVIDIA	Nvidia
de Koos, Andras	Microchip Technology Inc	Microchip Technology Inc
Djahanshahi, Hormoz	Microchip Technology, Inc.	Microchip Technology, Inc.
Dsilva, Hansel		Amphenol Corporation
Dudek, Michael	Marvell	Marvell
Elangovan, Vivekanandh	Infineon Technologies	Infineon Technologies
El-Chayeb, Ahmad	Keysight Technologies Inc	Keysight Technologies Inc
Enoki, Naomichi		Murata Electronics
Estrakh, Daniel	Valens Semiconductor	Valens Semiconductor

Fan, Xiaojie	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Ferretti, Vincent	Corning Incorporated	Corning Incorporated
Galan, Jose	MaxLinear, Inc.	MaxLinear, Inc.
Gareau, Sebastien		Ciena Corporation
Gauthier, Claude	NXP Semiconductors	NXP Semiconductors
Geng, Limin	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
George, John	Lightera	Lightera
Ghiasi, Ali	Ghiasi Quantum LLC	Ghiasi Quantum LLC; Marvell Semiconductor, Inc.
Gilb, James	General Atomics Aeronautical Systems, Inc.	General Atomics Aeronautical Systems, Inc.
Goel, Sachin	Aviva Links Inc	NXP
Goergen, Joel	Cisco Systems, Inc.	Cisco Systems, Inc.
Gorshe, Steven Scott	Microchip Technology, Inc.	Microchip Technology, Inc.
Goto, Hideki	Toyota Motor Corporation	Toyota Motor Corporation
Graber, Steffen	Pepperl+Fuchs SE	Pepperl+Fuchs SE
Gupta, Ajeya		General Motors Company
Hameed, Anil		Acsia Technologies
HE, MICHAEL	TeraHop Pte. Ltd.	TeraHop Pte. Ltd.
He, Xiang	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Healey, Adam	Broadcom Inc.	Broadcom Inc.
Heck, Howard	TE Connectivity	TE Connectivity
Hidaka, Yasuo	Credo Semiconductor	Credo Semiconductor
Hiroaki, Kukita	Yamaichi Electronics	Yamaichi Electronics
Hogenmueller, Thomas	Robert Bosch GmbH	Robert Bosch GmbH
Hu, Runlong		China Mobile Communications Group Co.,Ltd; China Mobile Communications Group Co.,Ltd
Huang, Kechao	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
HUANG, QINHUI	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Huber, Thomas	Nokia	Nokia
HYAKUTAKE, YASUHIRO	Orbray Co., Ltd.	Orbray Co., Ltd.
Isono, Hideki	Furukawa FITEL Optical Components Limited	Furukawa FITEL Optical Components
Issenhuth, Tom	Issenhuth Consulting, LLC	Huawei Technologies Co., Ltd
Iwasaki, Yutaka	Hirose Electric Co.,Ltd.	Hirose Electric Co., Ltd.
Jackson, Kenneth	Sumitomo Electric Industries, LTD	Sumitomo Electric Industries, LTD
Jeffreis, Brad		Analog Devices Inc.
Jin, Robert	Montage Technology, Inc	Montage Technology
Jochim, Markus	General Motors Company	General Motors Company
Johnson, John	Broadcom Corporation	Broadcom Corporation
Jones, Chad	Cisco Systems, Inc.	Cisco Systems, Inc.
Jones, Peter	Cisco Systems, Inc.	Cisco Systems, Inc.
Jonsson, Ragnar	Marvell Semiconductor, Inc.	Marvell

Kagami, Manabu	Nagoya Institute of Technology	Nagoya Institute of Technology (NITech)
Kapoor, Samay	Aviva Links	Aviva Links Inc.
Kareti, Upen	Cisco Systems, Inc.	Cisco Systems, Inc.
KATO, TAKAHIRO		Dexerials
Kim, Do Kyun	LG ELECTRONICS	LG ELECTRONICS
Kim, Gyudong	Analog Devices Inc.	Analog Devices Inc.
Kim, Yongbum	General Motors Company	General Motors Company
Kimber, Eric	Semtech Ltd	Semtech Ltd
Kleinwaechter, Mathias	in-tech GmbH	in-tech GmbH
Kochuparambil, Elizabeth	Cisco Systems, Inc.	Cisco Systems, Inc.
Kocsis, Sam	Amphenol Corporation	Amphenol Corporation
Lackner, Hans	QoSCom GmbH	QoSCom GmbH
Landry, Gary	Texas Instruments Inc.	Texas Instruments Inc.
Lasry, Ariel	Qualcomm Technologies, Inc	Qualcomm Technologies, Inc
Law, David	Hewlett Packard Enterprise	Hewlett Packard Enterprise
Lee, Ching-Yen		Realtek Semiconductor Corp.
Lee, Dongjae		Newracom Inc.
Lee, Sylvanus	Leviton Manufacturing Co.	Leviton Manufacturing Co.
Lessard, Stephane	Ericsson AB	Ericsson AB
Lewis, David	SPECIPHY / Lumentum	SPECIPHY, LUMENTUM
Lewis, Jon	Dell Technologies	Dell Technologies
Li, Mike-Peng	Altera Corporation	Advanced Micro Devices (AMD)
Li, Pei-Rong	MediaTek Inc.	MediaTek Inc.
Lim, Jane	Cisco Systems, Inc.	Cisco Systems, Inc.
Lin, YK		Realtek Semiconductor Corp.
Lin, Youxi	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Little, Terrance	Foxconn Electronics Inc.	Foxconn Electronics Inc.
Liu, Cathy	Broadcom Corporation	Broadcom Corporation
Lou, Wei		Broadcom Corporation
lu, chao	BMW Group	BMW Group
Luo, Yuanqiu	Futurewei Technologies	Futurewei Technologies
Lusted, Kent	Synopsys, Inc.	Synopsys, Inc.
Maguire, Valerie	Copperopolis	Copperopolis (aff'l with CME Consulting, Microchip, and NXP)
Maki, Jeffery	Hewlett Packard Enterprise	Hewlett Packard Enterprise
Mammenga, Kevin		Wilder Technologies
Maniloff, Eric	Ciena Corporation	Ciena Corporation
Mark, Simon	Würth Elektronik Group	Würth Elektronik Group
Marques, Flavio	Lightera	Lightera
Martinez Vazquez, Marcos	MaxLinear Corp	MaxLinear Inc
Martino, Kjersti	Inneos	Inneos
Mascitto, Marco	Infinera Canada Inc.	Nokia
Matuz, Balazs		Huawei Technologies Duesseldorf GmbH

McClellan, Brett	Marvell Semiconductor, Inc.	Marvell Semiconductor, Inc.
Mellitz, Richard	Samtec, Inc.	Samtec, Inc.
Messica, Barak		NVIDIA
mi, guangcan	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Miskho, Michael		Analog Devices Inc.
Muhigana, Ernest	MACOM Technology Solutions Holdings, Inc.	Macom Technology Solutions Inc
Muller, Shimon	Enfabrica Corp.	Enfabrica
Muma, Scott	Microchip Technology, Inc.	Microchip Technology, Inc.
MURAKAMI, YUKI	1Finity	1Finity
Murray, Brian	Analog Devices Inc.	Analog Devices Inc.
Murty, Ramana	Broadcom Inc.	Broadcom Corporation
Muth, Karlheinz	Broadcom Corporation	Broadcom Corporation
Nagaraja, Srikanth		Texas Instruments (India) Pvt. Ltd.; Texas Instruments Inc.
Nakamoto, Edward	Spirent Communications	VIAMI Solutions
Nering, Raymond	Cisco Systems, Inc.	Cisco Systems, Inc.
Nicholl, Gary	Cisco Systems, Inc.	Cisco Systems, Inc.
Nicholl, Shawn	Advanced Micro Devices (AMD)	Advanced Micro Devices (AMD)
NIIHARA, YOSHIHIRO	Fujikura Ltd.	Fujikura Ltd.
Ninomiya, Tiger	Accelink USA Corporation	Accelink USA Corporation
Nowell, Mark	Cisco Systems, Inc.	Cisco Systems, Inc.
Ofelt, David	Hewlett Packard Enterprise	Hewlett Packard Enterprise
Opsasnick, Eugene	Broadcom Inc.	Broadcom Inc.
Osorio, Luz		Nokia
Pal, Debajyoti		ON Semiconductor
Palkert, Thomas	Samtec, Inc.	Samtec, Inc.
Pan, Chunpo		Broadcom Corporation
Pandey, Sujan	Velinktech	Velinktech
Parkholm, Ulf	Telefon AB LM Ericsson	Ericsson AB
Parsons, Earl	CommScope, Inc.	CommScope, Inc.
Parthasarathy, Vasu	Broadcom Corporation	Broadcom Corporation
Peng, BC		MediaTek Inc.
peng, semmy	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Pepper, Gerald	Keysight Technologies	Keysight Technologies
Phadke, Rohan	Arista Networks	Arista Networks
Potterf, Jason	Cisco Systems, Inc.	Cisco Systems, Inc.
Quan, Yu	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Rabinovich, Rick	Keysight Technologies	Keysight Technologies
Ran, Adee	Cisco Systems, Inc.	Cisco Systems, Inc.
Ransford, Michael		Corning Incorporated
Razavi, Alireza	Marvell	Infineon Technologies
Reinhard, Michael	SEI Automotive Europe GmbH	SEI Automotive Europe GmbH
Ren, Hao	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Rodes, Roberto	II-VI	II-VI

Royer, Tyler	SENKO Advanced Components	SENKO Advanced Components
Rysin, Alexander	NVIDIA	NVIDIA
Sakai, Toshiaki	Socionext Inc.	socionext
Savi, Olindo	Hubbell Incorporated	Hubbell Incorporated
Schedl, Anton	BMW Group	BMW Group
Sekel, Steve	Wilder Technologies	wilder Technologeis
Shakiba, Mohammad	Huawei Technologies Canada Co., Ltd.	Huawei Technologies Canada; Huawei Technologies Co., Ltd
Sharma, Rohit		Molex Incorporated
She, Qingya	Fujitsu Network Communications	1FINITY
Shiino, Masato	FURUKAWA ELECTRIC	FURUKAWA ELECTRIC
Shrikhande, Kapil	Marvell Semiconductor, Inc.	Upscale AI
Sikkink, Mark	Hewlett Packard Enterprise	Hewlett Packard Enterprise
Simms, William	NVIDIA Corporation	NVIDIA Corporation
Slavick, Jeff	Broadcom Inc	Broadcom Inc
Sommers, Scott	Molex LLC	Molex Incorporated
Sorbara, Massimo	GLOBALFOUNDRIES	GLOBALFOUNDRIES
Spruit, Hans	TRUMPF	Western Digital Corporation
Stephens, Jeremy	Advanced Micro Devices (AMD)	Advanced Micro Devices (AMD)
Strohmeier, Heiko	Robert Bosch GmbH	Robert Bosch GmbH
Sun, jingcong	Motorcomm Electronic Technology Co	Motorcomm Electronic Technology Co
Sun, Yi	Lightera	Lightera
Swenson, Norman	Norman Swenson Consulting	Norman Swenson Consulting; Point2 Technology Inc.; Nokia
TAKAHARA, TOMOO	FUJITSU LABORATORIES LIMITED	1FINITY
TAKEUCHI, JUNICHI	JAE Electronics, Inc	JAE Electronics, Inc.
Tan, Yuxuan	Motorcomm	Motorcomm
Tanz, Simon		BMW AG; BMW Group
TAZEBAY, MEHMET	Broadcom Corporation	Broadcom Corporation
Theodoras, James	Scintil Photonics	Scintil Photonics
Thomas, Rajan		Acsia Technologies
Thompson, Geoffrey	GraCaSI S.A.	INDEPENDENT
Toyserkani, Pirooz	Cisco Systems, Inc.	Cisco Systems, Inc.
Torres, Luisma	Knowledge Development for POF SL	KD
Tracy, Nathan	TE Connectivity	TE Connectivity
Tran, Viet	Keysight Technologies	Keysight Technologies
Tu, Mike	Broadcom Corporation	Broadcom Corporation
Turner, Max	Ethernovia	Ethernovia
Umar, Ashraf		Molex Incorporated
Urban, Luke		Magnolia Electronics
Vanderlaan, Paul	UL Solutions	Panduit Corp.
Veloso Cauce, Gumersindo	BMW Group	BMW AG; BMW Group
Venkataraman, Srinivas	Broadcom Corporation	Broadcom Corporation
Voss, Robert	Panduit Corp.	Panduit Corp.

Wang, Haojie	China Mobile Communications Corporation (CMCC)	China Mobile Communications Corporation (CMCC)
Wang, Ruoxu	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Wang, Shun-Sheng	Realtek Semiconductor Corp.	Realtek Semiconductor Corp.
wang, weilai	BMW Group	BMW AG; BMW Group
Wang, Xiaofeng	Qualcomm Incorporated	Qualcomm Incorporated
WANG, Xuebo	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Watanabe, Yojiro	Mitsubishi Electric US, Inc.	Mitsubishi Electric US, Inc.
Weaver, James	Arista Networks	Arista Networks
Wei, Terry		Analog Devices Inc.
Welch, Brian	Cisco Systems, Inc.	Luxtera
Wienckowski, Natalie	IVN Solutions LLC	IVN Solutions LLC; Ethernovia
Wig, Timothy	Samtec, Inc.	Samtec, Inc.
Wingrove, Michael	Ciena Corporation	Ciena Corporation
Withey, James	Fluke Corporation	Fluke Corporation
Wu, Dance	Marvell Semiconductor, Inc.	Infineon Technologies
Wu, Peter	Marvell Semiconductor, Inc.	Marvell Semiconductor, Inc.
XU, LI	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
xu, wenxiong	HG Genuine	HGGenuine
Xu, Yu	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Yamazaki, Kinya	APRESIA Systems	APRESIA Systems
Yin, Shuang		Google
Zerna, Conrad	Aviva Links Inc	NXP Semiconductors
Zhang, Tingting	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Zhang, Wei		Broadcom Corporation
Zhu, Keyi		HUAWEI
ZHU, YUE		Huawei Technologies Co., Ltd
Zhuang, Yan	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Zimmerman, George	CME Consulting, Inc.	CME Consulting/Analog Devices, APL Group, Cisco, Infineon, OnSemi, Sony
Zivny, Pavel	MultiLane	MultiLane
Zou, Congshi	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd